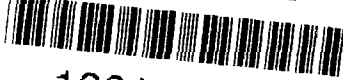

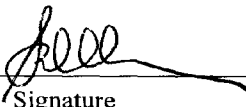


11/15/05

12-06-2005

FORM PTO-1595 (Rev. 10/02)		REC			U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office	
Docket No.: 069576-0035						
To the Honorable Commissioner for Patents and Trademarks: 103130888 original documents or copy thereto:						
1. Name of Conveying Party(ies): Byoung Hwa LEE, Chang Hoon SHIM, Kyong Nam HWANG, Dong Seok PARK, Sang Soo PARK, and Min Cheol PARK			2. Name and address of receiving party(ies): Name: SAMSUNG ELECTRO-MECHANICS CO., LTD. Address: 314 Maetan-3-dong, Youngtong-ku Suwon, Kyungki-do Republic of Korea			
Additional name(s) of conveying party(ies) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No			112963 U.S. PTO 11/272877  111505			
3. Nature of Conveyance: <input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger <input type="checkbox"/> Security Agreement <input type="checkbox"/> Change of Name <input type="checkbox"/> Other Execution Date: November 7, 2005						
4. Application number(s) or patent number(s): If the document is being filed together with a new application, the execution date of the application is: November 7, 2005 A. Patent Application No(s). B. Patent No(s). Additional numbers attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No						
5. Name and address of party to whom correspondence concerning document should be mailed: Name: MCDERMOTT WILL & EMERY LLP Internal Address: Street Address: 600 13th Street, N.W. City: Washington State: D. C. Zip: 20005-3096			6. Total number of applications and patents involved: 1 7. Total fee (37 CFR 3.41) \$40.00 <input type="checkbox"/> Enclosed <input checked="" type="checkbox"/> Authorized to be charged to deposit account 8. Deposit account number: 500417			
DO NOT USE THIS SPACE						
9. Statement and signature. <i>To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.</i> Stephen A. Becker, Registration No. 26,527 Name and Registration No. of Person Signing  Signature November 15, 2005 Date Total number of pages including cover sheet: 3						
OMB No. 0651-0027 (exp. 6/30/2005)						

12/05/2005 ECOOPER 00000274 500417 11272877

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40.00 DA

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

(1) <u>LEE, Byoung Hwa</u>	(4) <u>PARK, Dong Seok</u>
(2) <u>SHIM, Chang Hoon</u>	(5) <u>PARK, Sang Soo</u>
(3) <u>HWANG, Kyong Nam</u>	(6) <u>PARK, Min Cheol</u>

who have made a certain new and useful invention, hereby sell, assign and transfer unto

SAMSUNG ELECTRO-MECHANICS CO., LTD.
314 Maetan-3-dong, Youngtong-ku, Suwon, Kyungki-do, Republic of Korea

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

MULTI-LAYER CHIP CAPACITOR

(a) for which an application for United States Letters Patent was filed on _____,
and identified by United States Serial No. _____; or

(b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the dates indicated aside our signatures:

INVENTORS	DATE SIGNED
1) <u>LEE Byoung Hwa</u> Name: LEE, Byoung Hwa	<u>November 7, 2005</u>
2) <u>Chang Hoon Shin</u> Name: SHIM, Chang Hoon	<u>November 7, 2005</u>
3) <u>hwang</u> Name: HWANG, Kyong Nam	<u>November 7, 2005</u>

- 4) Park November 7, 2005
Name: PARK, Dong Seok
- 5) P. Sang Soo November 7, 2005
Name: PARK, Sang Soo
- 6) Park Min Cheol November 7, 2005
Name: PARK, Min Cheol